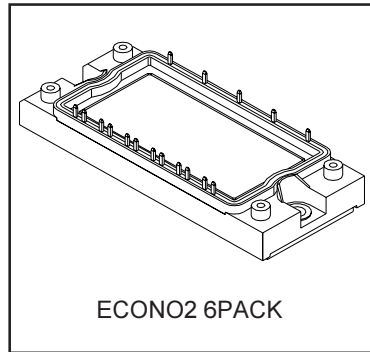


IGBT SIXPACK MODULE

Features

- Low V_{CE} (on) Non Punch Through IGBT Technology
- Low Diode VF
- 10μs Short Circuit Capability
- Square RBSOA
- HEXFRED Antiparallel Diode with Ultrasoft Reverse Recovery Characteristics
- Positive V_{CE} (on) Temperature Coefficient
- Ceramic DBC Substrate
- Low Stray Inductance Design




$$V_{CES} = 1200V$$

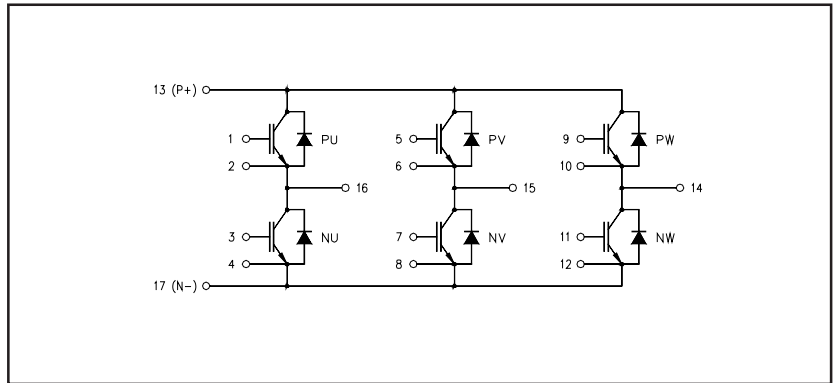
$$I_C = 50A @ T_C=80^{\circ}C$$

$$t_{sc} > 10\mu s @ T_J=150^{\circ}C$$

$$V_{CE(on)} \text{ typ.} = 2.45V$$

Benefits

- Benchmark Efficiency for Motor Control
- Rugged Transient Performance
- Low EMI, Requires Less Snubbing
- Direct Mounting to Heatsink
- PCB Solderable Terminals
- Low Junction to Case Thermal Resistance
- UL Approved E78996 



Absolute Maximum Ratings

	Parameter	Max.	Units
V _{CES}	Collector-to-Emitter Voltage	1200	V
I _C @ T _C =25°C	Continuous Collector Current	75	A
I _C @ T _C =80°C	Continuous Collector Current	50	
I _{CM}	Pulsed Collector Current (Ref. Fig. C.T.5)	150	
I _{LM}	Clamped Inductive Load Current	150	
I _F @ T _C =25°C	Diode Continuous Forward Current	75	
I _F @ T _C =80°C	Diode Continuous Forward Current	50	
I _{FM}	Pulsed Diode Maximum Forward Current	150	
V _{GE}	Gate-to-Emitter Voltage	±20	V
P _D @ T _C =25°C	Maximum Power Dissipation (IGBT and Diode)	329	W
P _D @ T _C =80°C	Maximum Power Dissipation (IGBT and Diode)	184	
T _J	Maximum Operating Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	-40 to +125	
V _{ISOL}	Isolation Voltage	AC 2500 (MIN)	V

Thermal and Mechanical Characteristics

	Parameter	Min	Typical	Maximum	Units
R _{θJC} (IGBT)	Junction-to-Case IGBT	-	-	0.38	°C/W
R _{θJC} (Diode)	Junction-to-Case Diode	-	-	0.70	
R _{θCS} (Module)	Case-to-Sink, flat, greased surface	-	0.05	-	
	Mounting Torque (M5)	2.7	-	3.3	N*m
	Weight	-	170	-	g

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV _(CES)	Collector-to-Emitter Breakdown Voltage	1200	-	-	V	V _{GE} = 0 I _C = 500μA
ΔV _{(BR)CES/ΔT_J}	Temp. Coefficient of Breakdown Voltage	-	0.31	-	V/°C	V _{GE} = 0 I _C = 1mA (25°C - 125°C)
V _{CE(ON)}	Collector-to-Emitter Voltage	-	2.45	2.65	V	I _C = 50A V _{GE} = 15V
		-	2.85	3.15		I _C = 75A V _{GE} = 15V
		-	2.85	-		I _C = 50A V _{GE} = 15V T _J = 125°C
		-	3.45	-		I _C = 75A V _{GE} = 15V T _J = 125°C
V _{GE(th)}	Gate Threshold Voltage	4.0	4.9	6.0		V _{CE} = V _{GE} I _C = 250μA
ΔV _{GE(th)/ΔT_J}	Threshold Voltage temp. coefficient	-	-12	-	mV/°C	V _{CE} = V _{GE} I _C = 1mA (25°C-125°C)
I _{CES}	Zero Gate Voltage Collector Current	-	-	100	μA	V _{GE} = 0 V _{CE} = 1200V
		-	1000	-		V _{GE} = 0 V _{CE} = 1200V T _J = 125°C
V _{FM}	Diode Forward Voltage Drop	-	1.95	2.25	V	I _F = 50A
		-	2.20	2.60		I _F = 75A
		-	2.05	-		I _F = 50A T _J = 125°C
		-	2.40	-		I _F = 75A T _J = 125°C
I _{GES}	Gate-to-Emitter Leakage Current	-	-	±200	nA	V _{GE} = ±20V

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q _G	Total Gate Charge (turn-on)	-	355	535	nC	I _C = 50A
Q _{GE}	Gate-to-Emitter Charge (turn-on)	-	35	55		V _{CC} = 600A
Q _{GC}	Gate-to-Collector Charge (turn-on)	-	165	250		V _{GE} = 15V
E _{ON}	Turn-On Switching Loss	-	3600	4635	μJ	I _C = 50A V _{CC} = 600V
E _{OFF}	Turn-Off Switching Loss	-	3740	4780		V _{GE} = 15V R _G = 10Ω L = 400μH
E _{TOT}	Total Switching Loss	-	7340	9415		T _J = 25°C ①
E _{ON}	Turn-On Switching Loss	-	5050	7100	μJ	I _C = 50A V _{CC} = 600V
E _{OFF}	Turn-Off Switching Loss	-	5525	7750		V _{GE} = 15V R _G = 10Ω L = 400μH
E _{TOT}	Total Switching Loss	-	10575	14850		T _J = 125°C ①
t _{d(on)}	Turn-On delay time	-	60	80	ns	I _C = 50A V _{CC} = 600V
t _r	Rise time	-	40	60		V _{GE} = 15V R _G = 10Ω L = 400μH
t _{d(off)}	Turn-Off delay time	-	570	665		T _J = 125°C
t _f	Fall time	-	205	270		
C _{ies}	Input Capacitance	-	4945	-	pF	V _{GE} = 0
C _{oes}	Output Capacitance	-	885	-		V _{CC} = 30V
C _{res}	Reverse Transfer Capacitance	-	100	-		f = 1Mhz
RBSOA	Reverse Bias Safe Operating Area	FULLSQUARE				T _J = 150°C I _C = 150A R _G = 10Ω V _{GE} = 15V to 0
SCSOA	Short Circuit Safe Operating Area	10	-	-	μs	T _J = 150°C V _{CC} = 900V V _P = 1200V R _G = 10Ω V _{GE} = 15V to 0
I _{rr}	Diode Peak Rev. Recovery Current	-	87	-	A	T _J = 125°C V _{CC} = 600V I _F = 50A L = 400μH V _{GE} = 15V R _G = 10Ω

① Energy losses include "tail" and diode reverse recovery.

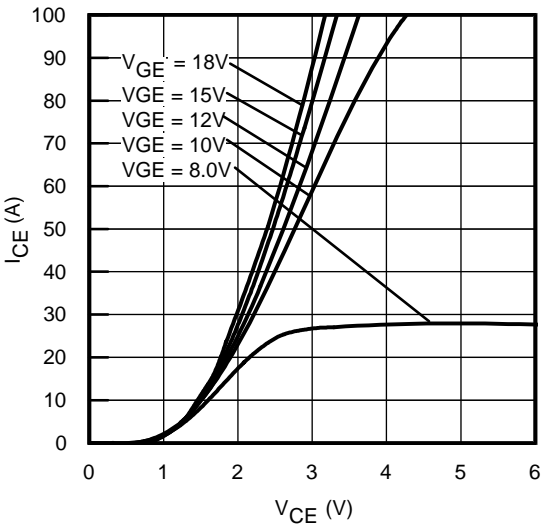


Fig. 1 - Typ. IGBT Output Characteristics
 $T_J = 25^\circ\text{C}$; $t_p = 80\mu\text{s}$

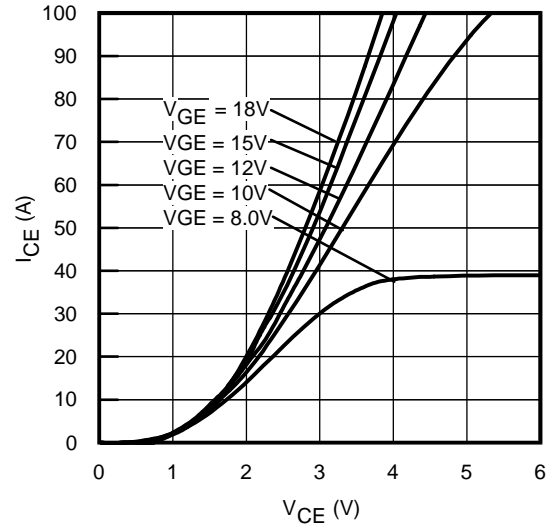


Fig. 2 - Typ. IGBT Output Characteristics
 $T_J = 125^\circ\text{C}$; $t_p = 80\mu\text{s}$

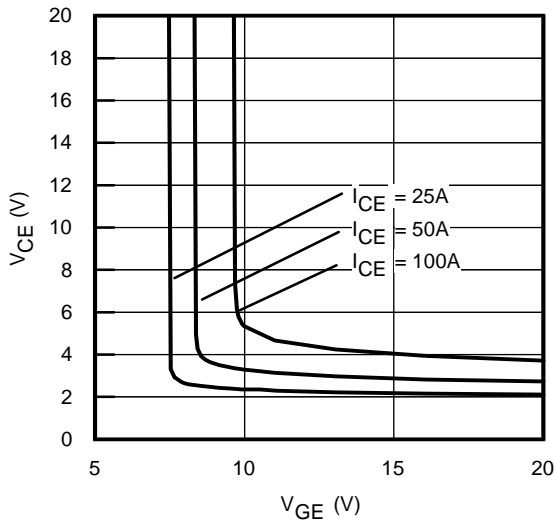


Fig. 3 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

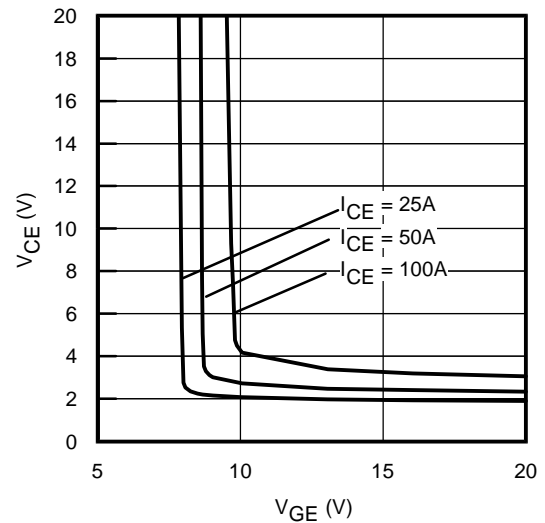


Fig. 4 - Typical V_{CE} vs. V_{GE}
 $T_J = 125^\circ\text{C}$

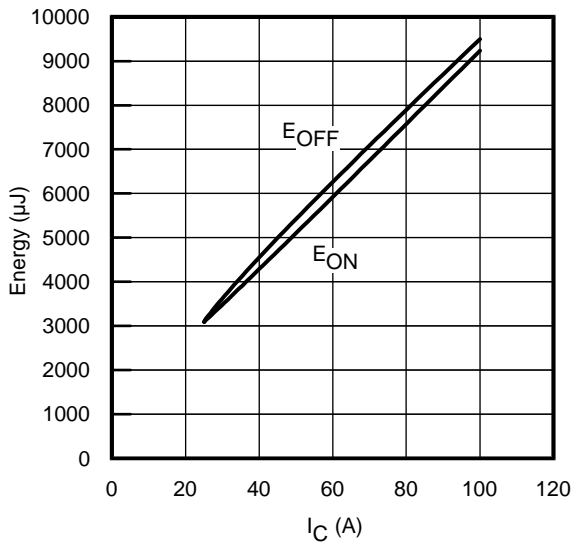


Fig. 5 - Typ. Energy Loss vs. I_C
 $T_J = 125^\circ\text{C}$; $L = 400\mu\text{H}$; $V_{CE} = 600\text{V}$
 $R_G = 10\Omega$; $V_{GE} = 15\text{V}$

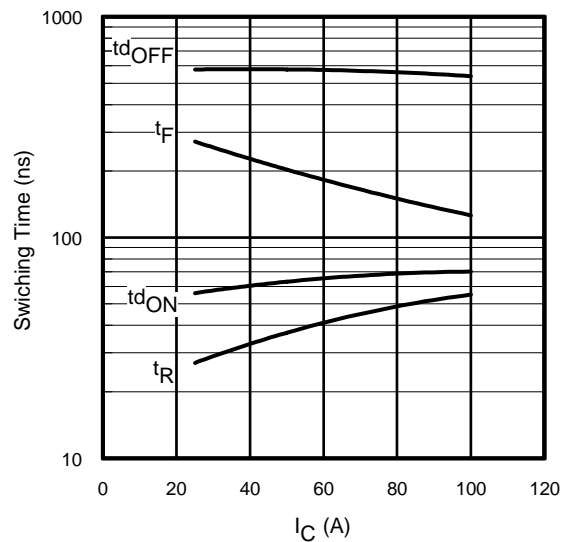


Fig. 6 - Typ. Switching Time vs. I_C
 $T_J = 125^\circ\text{C}$; $L = 400\mu\text{H}$; $V_{CE} = 600\text{V}$
 $R_G = 10\Omega$; $V_{GE} = 15\text{V}$

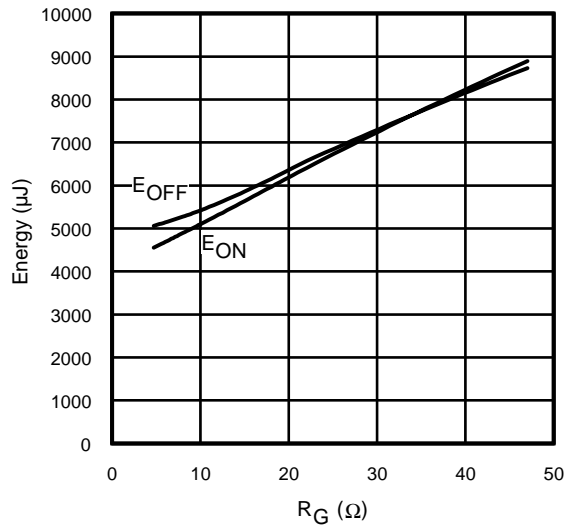


Fig. 7 - Typ. Energy Loss vs. R_G
 $T_J = 125^\circ\text{C}$; $L=400\mu\text{H}$; $V_{CE}=600\text{V}$
 $I_{CE}=50\text{A}$; $V_{GE}=15\text{V}$

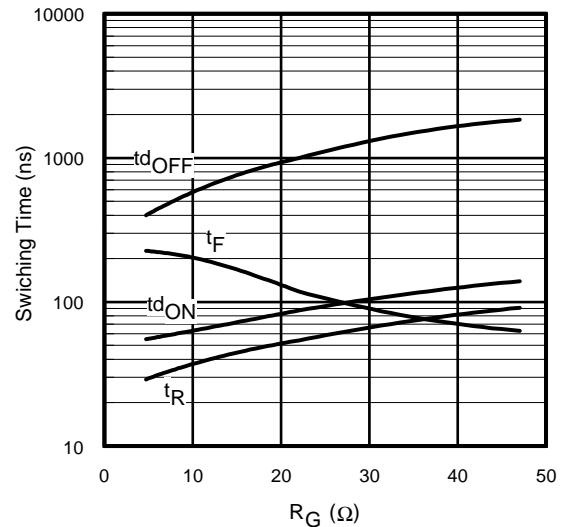


Fig. 8 - Typ. Switching Time vs. R_G
 $T_J = 125^\circ\text{C}$; $L=400\mu\text{H}$; $V_{CE}=600\text{V}$
 $I_{CE}=50\text{A}$; $V_{GE}=15\text{V}$

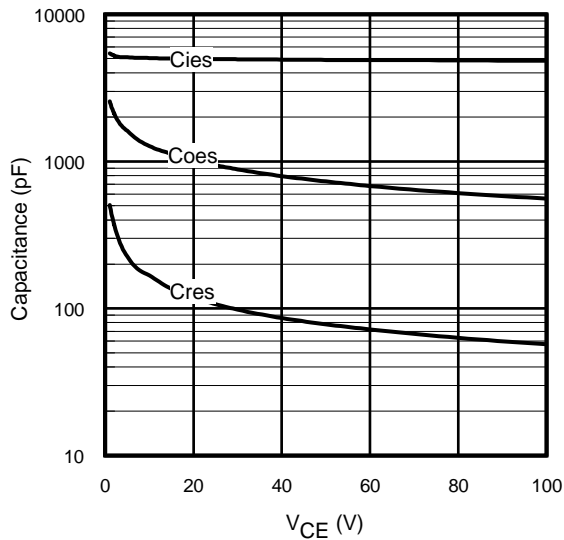


Fig. 9 - Typ. Capacitance vs. V_{CE}
 $V_{GE}=0\text{V}$; $f=1\text{MHz}$

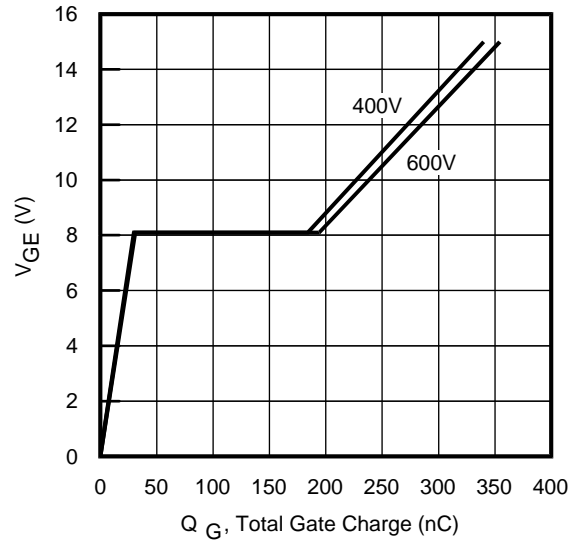


Fig. 10 - Typical Gate Charge vs. V_{GE}
 $I_{CE}=50\text{A}$; $L=600\mu\text{H}$

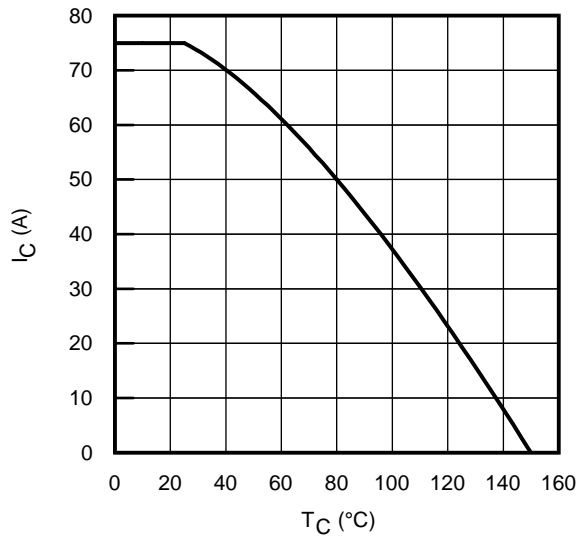


Fig. 11 - Maximum DC Collector Current vs. Case Temperature

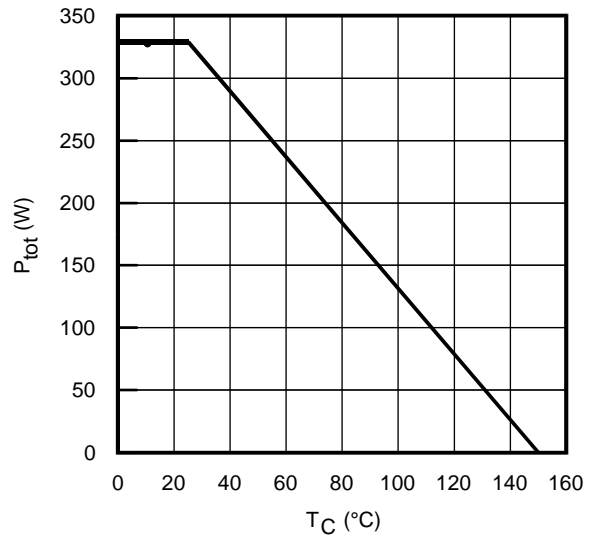


Fig. 12 - Power Dissipation vs. Case Temperature

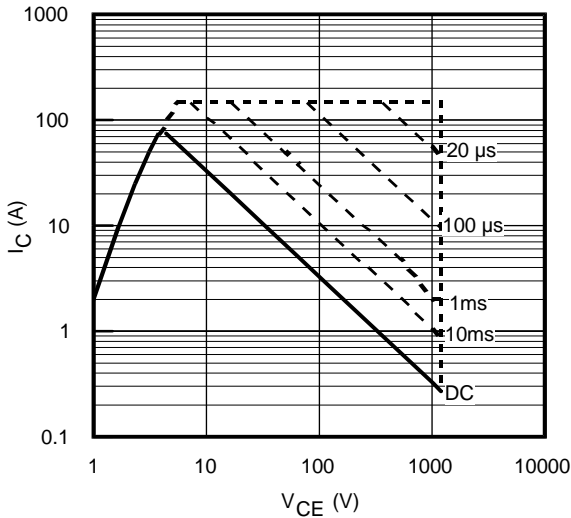


Fig. 13 - Forward SOA
 $T_C = 25^\circ\text{C}; T_J \leq 150^\circ\text{C}$

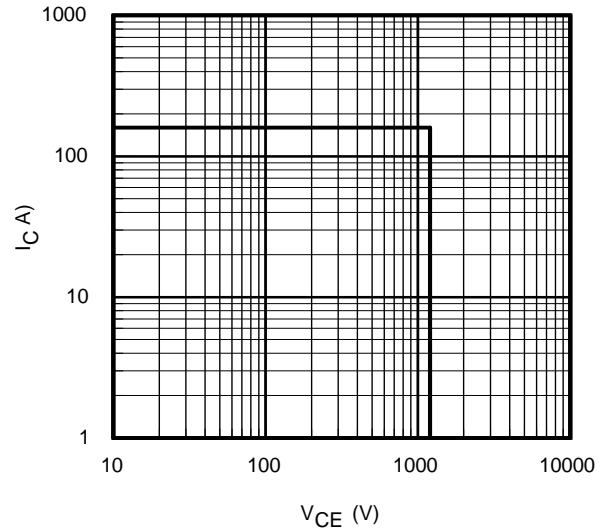


Fig. 14 - Reverse Bias SOA
 $T_J = 150^\circ\text{C}; V_{GE} = 15\text{V}$

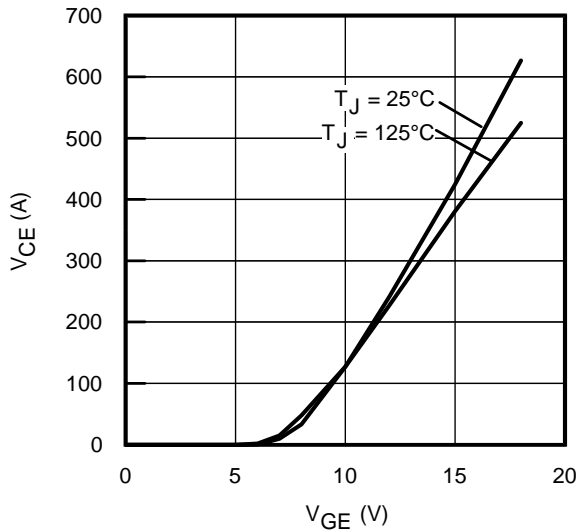


Fig. 15 - Typ. Transfer Characteristics
 $V_{CE} = 50\text{V}; t_p = 10\mu\text{s}$

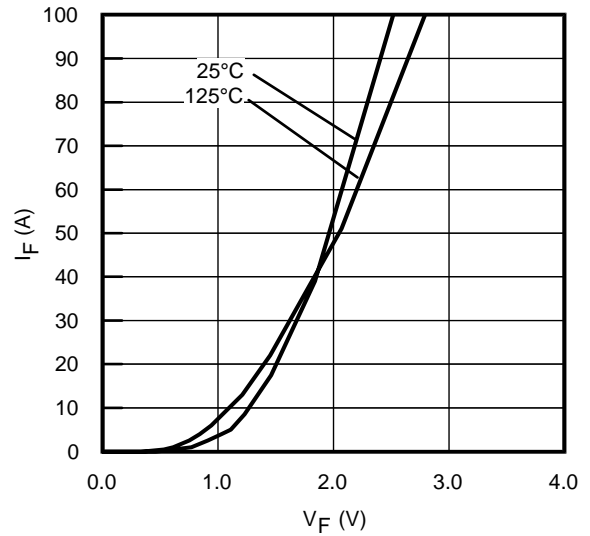


Fig. 16 - Typ. Diode Forward Characteristics
 $t_p = 80\mu\text{s}$

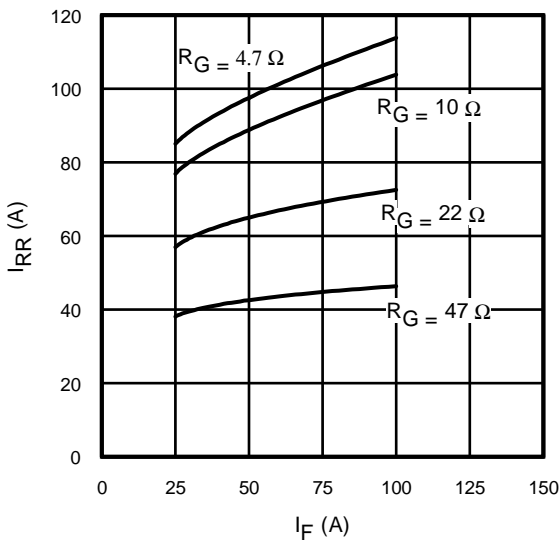


Fig. 17 - Typical Diode I_{RR} vs. I_F
 $T_J = 125^\circ\text{C}$

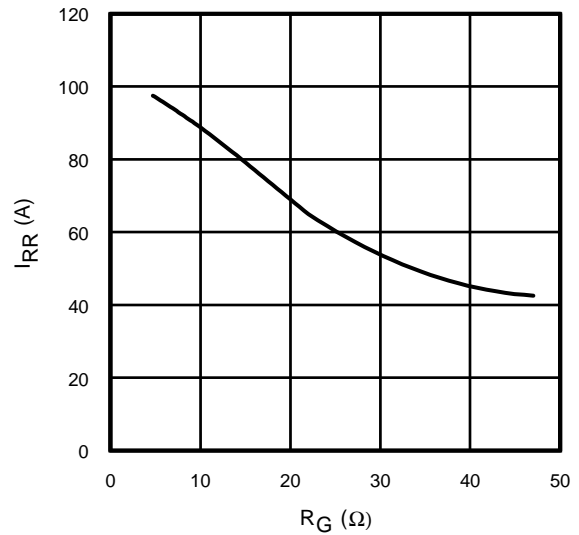


Fig. 18 - Typical Diode I_{RR} vs. R_G
 $T_J = 125^\circ\text{C}; I_F = 50\text{A}$

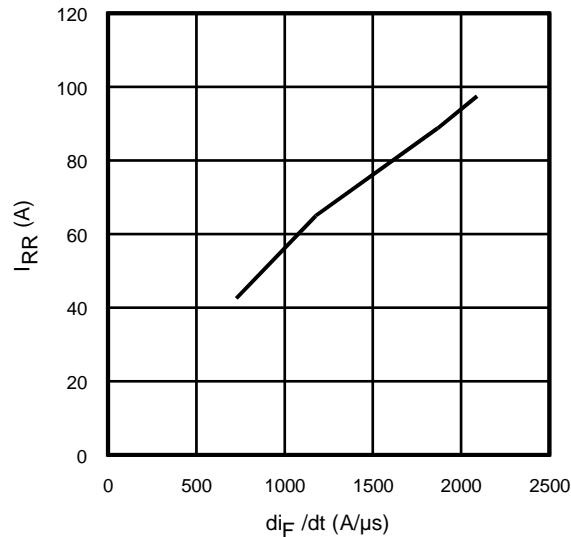


Fig. 19- Typical Diode I_{RR} vs. di_F/dt ; $V_{CC}=600V$; $V_{GE}=15V$; $I_{CE}=50A$; $T_J=125^{\circ}C$

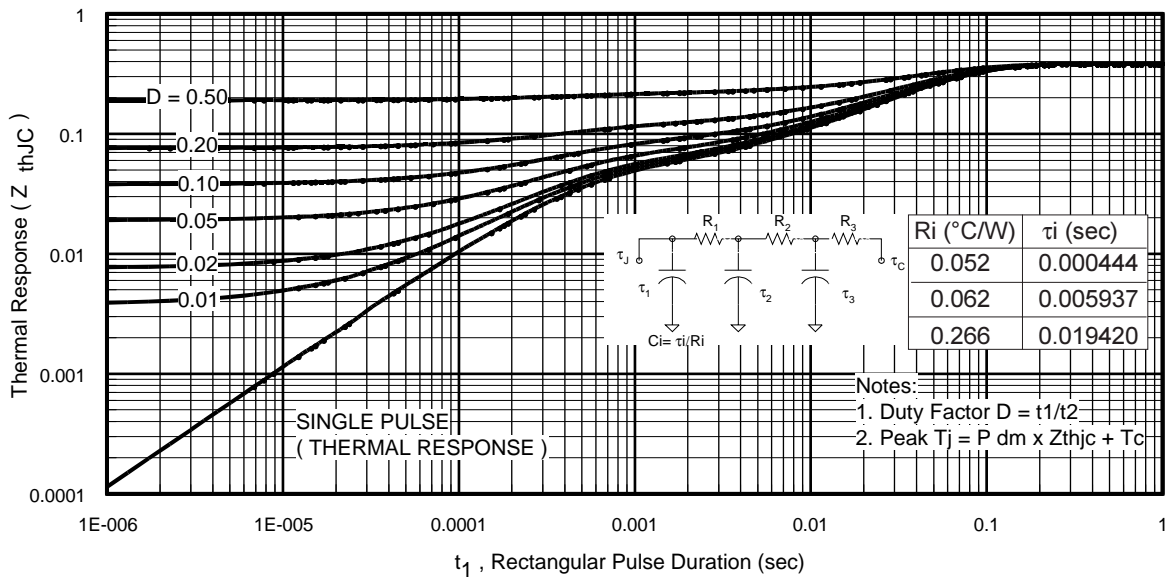


Fig 20. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

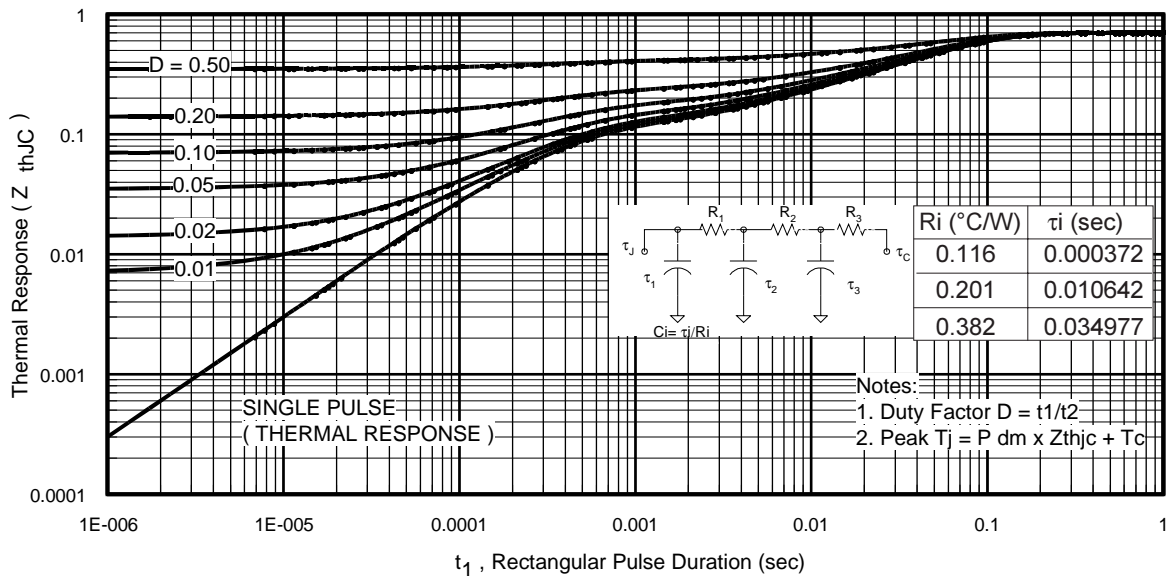


Fig 21. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

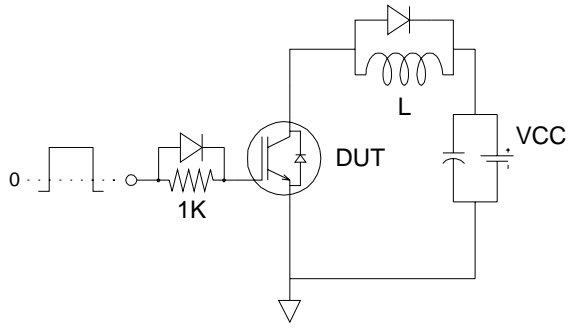


Fig.C.T.1 - Gate Charge Circuit (turn-off)

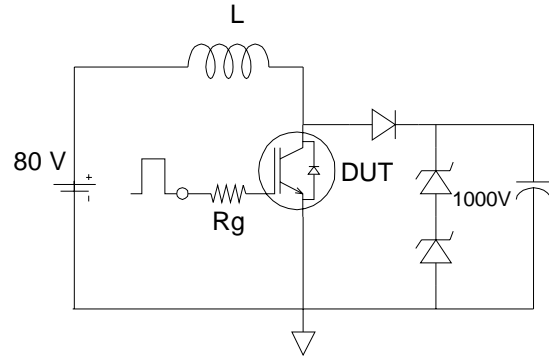


Fig.C.T.2 - RBSOA Circuit

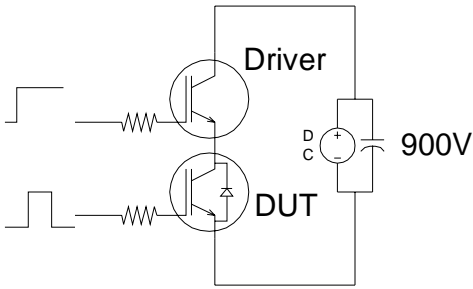


Fig.C.T.3 - S.C. SOA Circuit

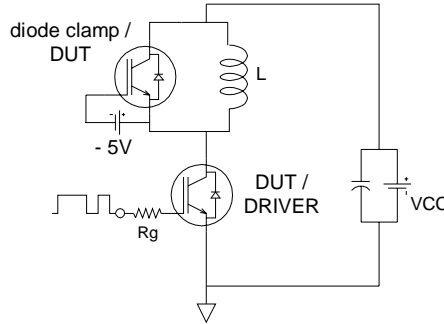


Fig.C.T.4 - Switching Loss Circuit

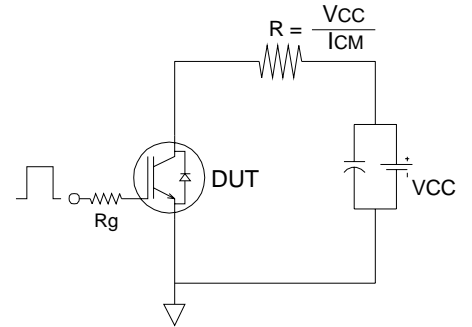


Fig.C.T.5 - Resistive Load Circuit

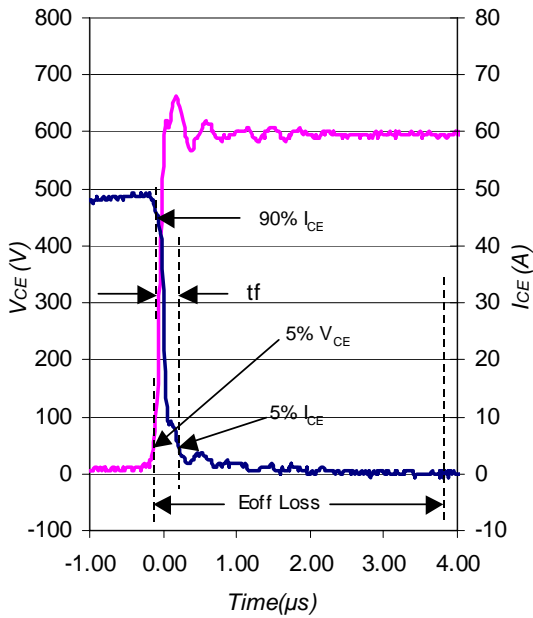


Fig. WF1-Typ. Turn-off Loss Waveform
@ $T_J = 125^\circ\text{C}$ using Fig. CT.4

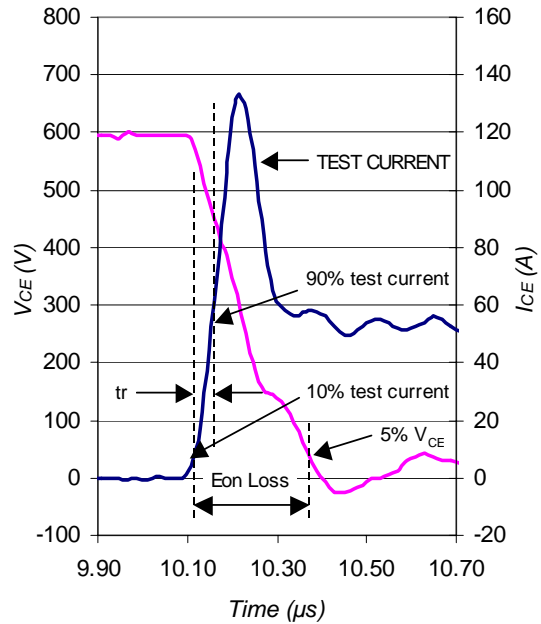


Fig. WF2-Typ. Turn-on Loss Waveform
@ $T_J = 125^\circ\text{C}$ using Fig. CT.4

